

LEADED

BGA SOLDER PASTE

● ● ●
Sn63/Pb37

Melting point 183°C



Product Usage

● ● ●
TIN PASTE

| | |
|---------------|--------------|
| Type number | BST-506 |
| Types of | Solder Paste |
| Composition | Sn63/Pb37 |
| Melting point | 183°C |
| G.W. | 50g |
| size | 36*36mm |



Sn63/Pb37

Melting point at medium temperature

183°C



Low residue



Solder spot bright



Rapid welding

Welding requirements for a wide range of products



SMT
patch



LED
patch



BGA
welding



Product List

G.W.:50g

